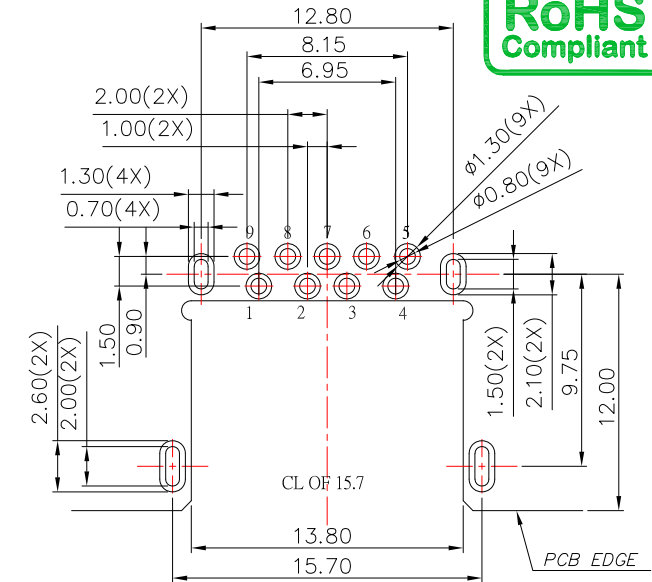
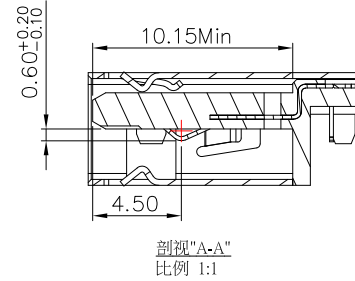
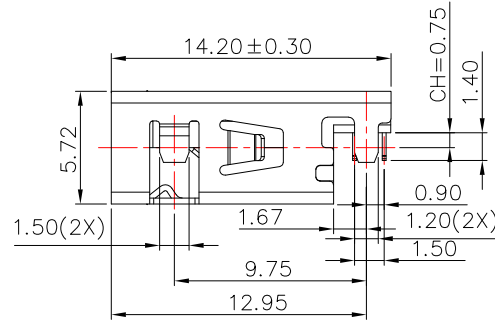
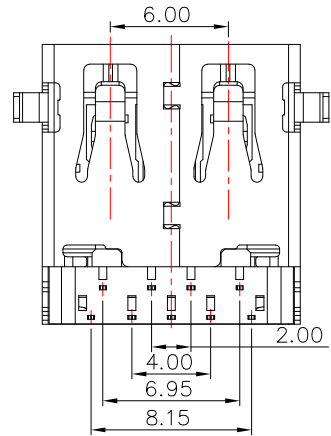
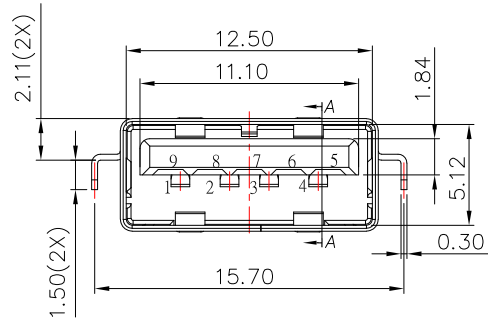
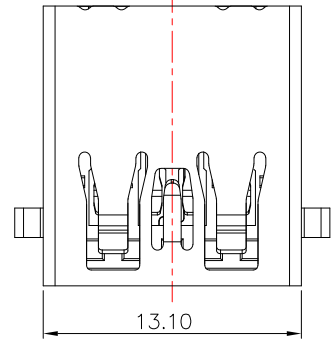




SUA-110E26-30x-S277

鍍層厚度:

Blank : 1u"
2 : 15u"
3 : 30u"



PCB LAYOUT TOP VIEW

NOTE:

1.MATERIAL:

- 1.1 Housing: PA9T
- 1.2 Contact: Phosphor Bronze
- 1.3 Shell: SUS

2.Finish:

- 2.1 Contact: Plated Gold in Mating Area ;
Tin Plated on Solder Balls ;
Nickel under plated overall
- 2.2 Shell: Nickel under Plated surface layer

3.SPECIFICATION:

- 3.1 Rate: 1.8 A
- 3.2 insulator Resistance:100MΩ Min
- 3.3 Dielectric Strength: 100V AC
- 3.4 Contact Resistance: 30mΩ Max
- 3.5 Insertion Force: 35 N
- 3.6 Extraction Force: 10 N

USB 3.0 PIN ASSIGNMENTS

Pin #	SIGNAL NAME	DESCRIPTION	MATING SEQUENCE
1	VBUS	POWER	SECOND
2	D-	USB 2.0 DIFFERENTIAL PAIR	THIRD
3	D+		
4	GND	GROUND FOR POWER RETURN	SECOND
5	StdA_SSRX-	SUPER SPEED RECEIVER DIFFERENTIAL PAIR	LAST
6	StdA_SSRX+		
7	GND_DRAIN	GROUND FOR SIGNAL RETURN	
8	StdA_SSTX-	SUPER SPEED TRANSMITTER DIFFERENTIAL PAIR	
9	StdA_SSTX+		
Shell	Shield	CONNECTOR METAL SHELL	FRIST

CONTACT 建倚科技股份有限公司
CONTACT TECHNOLOGY CORP.

TOLERANCE UNLESS OTHERWISE STATED :
Up to 5 ±0.2
Above 5 ~ 15 ±0.3
Above 15 ~ 30 ±0.4
Above 30 ~ 50 ±0.5
Angle ±0.3

3RD.
ANGEL'S



UNITS

MM

DRAWN BY:	DATE	MAT'L		TITLE	CONNECTOR
Jack Lu	04/30/26	FINISH		MODLE	USB AF 3.0 沉板DIP 板上H2.11mm CL0.75 無捲邊
CHECKED BY:	DATE	SCALE	1 : 1	DWG NO.	SUA-110E26-30x-S277
Jacky Chen	04/30/26	SHEET NO.	1 of 1	PART NO.	SUA-110E26-30x-S277
APPROVED BY:	DATE				
Tony Kao	04/30/26				